

SNx4HC109 Dual J- \bar{K} Positive-Edge-Triggered Flip-Flops With Clear and Preset

1 Features

- Wide operating voltage range of 2 V to 6 V
- Low input current of 1 μ A max
- High-current outputs drive up to 10 LSTTL loads
- Low power consumption, 40- μ A max I_{CC}
- Typical $t_{pd} = 12$ ns
- ± 4 -mA output drive at 5 V

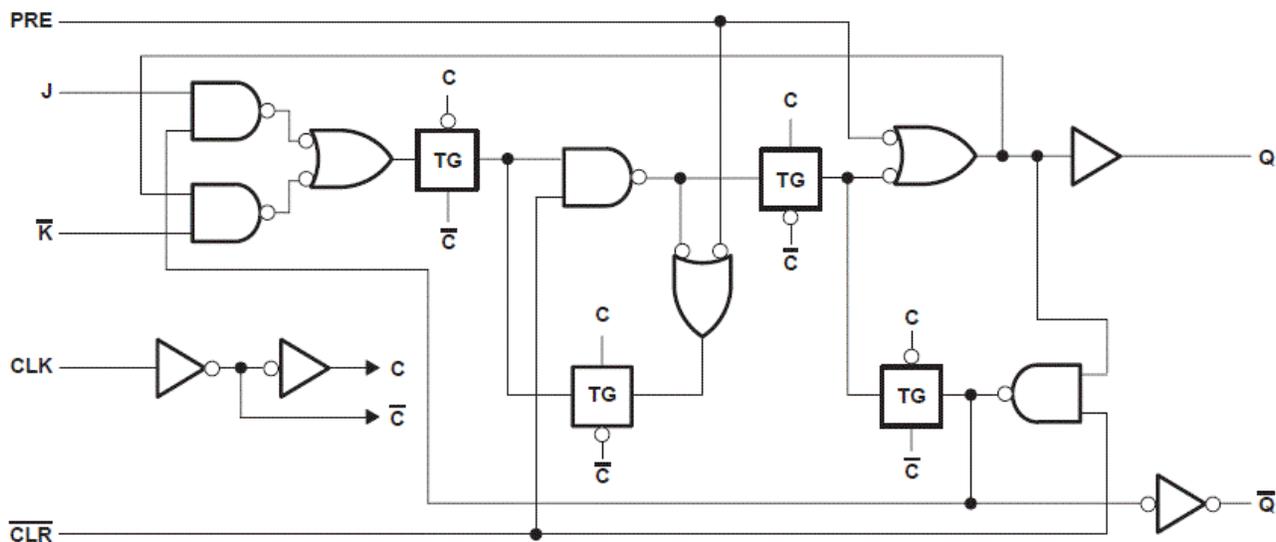
2 Description

These devices contain two independent J- \bar{K} positive-edge-triggered flip-flops. A low level at the preset (\overline{PRE}) or clear (\overline{CLR}) inputs sets or resets the outputs, regardless of the levels of the other inputs. When \overline{PRE} and \overline{CLR} are inactive (high), data at the J and \bar{K} inputs meeting the setup-time requirements are transferred to the outputs on the positive-going edge of the clock (CLK) pulse. Clock triggering occurs at a voltage level and is not related directly to the rise time of the clock pulse. Following the hold-time interval, data at the J and \bar{K} inputs can be changed without affecting the levels at the outputs. These versatile flip-flops can perform as toggle flip-flops by grounding \bar{K} and tying J high. They also can perform as D-type flip-flops if J and \bar{K} are tied together.

Device Information

PART NUMBER	PACKAGE ⁽¹⁾	BODY SIZE (NOM)
SN54HC109J	CDIP (16)	24.38 mm \times 6.92 mm
SN74HC109D	SOIC (16)	9.90 mm \times 3.90 mm
SN74HC109N	PDIP (16)	19.31 mm \times 6.35 mm
SN74HC109NS	SO (16)	6.20 mm \times 5.30 mm
SNJ54HC109FK	LCCC (20)	8.89 mm \times 8.45 mm
SNJ54HC109W	CFP (16)	10.16 mm \times 6.73 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.



Functional Block Diagram



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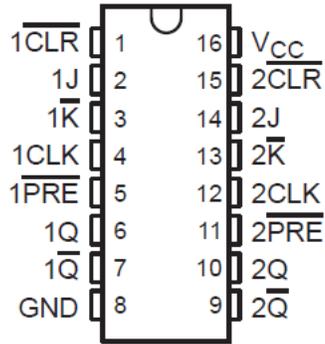
3 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

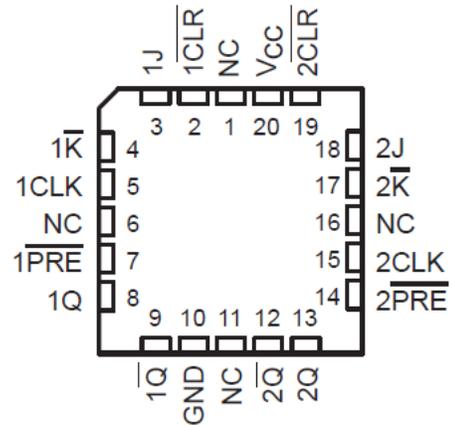
Changes from Revision B (February 2022) to Revision C (June 2022)	Page
• Junction-to-ambient thermal resistance values increased. D was 73 is now 117.2, N was 67 is now 60.5, NS was 64 is now 88.3.....	4

Changes from Revision A (October 2003) to Revision B (February 2022)	Page
• Updated the numbering, formatting, tables, figures, and cross-references throughout the document to reflect modern data sheet standards.....	1

4 Pin Configuration and Functions



J, W, D, N, or NS Package
16-Pin CDIP, CFP, SOIC, PDIP, or SO
Top View



NC - No internal connection

FK Package
20-Pin LCCC
Top View

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

			MIN	MAX	UNIT
V _{CC}	Supply voltage range		-0.5	7	V
I _{IK}	Input clamp current	V _I < 0 or V _I > V _{CC}		±20	mA
I _{OK}	Output clamp current	V _O < 0 or V _O > V _{CC}		±20	mA
I _O	Continuous output current	V _O = 0 to V _{CC}		±35	mA
	Continuous current through V _{CC} or GND			±70	mA
	Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds	FK package		300	°C
		J package			
		W package			
	Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	D package		260	°C
		N package			
		NS package			
T _J	Junction temperature			150	°C
T _{stg}	Storage temperature range		-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

5.2 Recommended Operating Conditions⁽¹⁾

			SN54HC109			SN74HC109			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage		2	5	6	2	5	6	V
V _{IH}	High-level input voltage	V _{CC} = 2 V	1.5			1.5			V
		V _{CC} = 4.5 V	3.15			3.15			
		V _{CC} = 6 V	4.2			4.2			
V _{IL}	Low-level input voltage	V _{CC} = 2 V	0.3			0.5			V
		V _{CC} = 4.5 V	0.9			1.35			
		V _{CC} = 6 V	1.2			1.8			
V _I	Input voltage		0	V _{CC}		0	V _{CC}		V
V _O	Output voltage		0	V _{CC}		0	V _{CC}		V
Δt/Δv	Input transition rise/fall time	V _{CC} = 2 V	1000			1000			ns
		V _{CC} = 4.5 V	500			500			
		V _{CC} = 6 V	400			400			
T _A	Operating free-air temperature		-55	125		-40	85		°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

5.3 Thermal Information

THERMAL METRIC		D (SOIC)	N (PDIP)	NS (SO)	UNIT
		16 PINS	16 PINS	16 PINS	
R _{θJA}	Junction-to-ambient thermal resistance ⁽¹⁾	117.2	60.5	88.3	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	77.2	47.9	45.9	°C/W
R _{θJB}	Junction-to-board thermal resistance	75.6	40.4	50.9	°C/W

5.3 Thermal Information (continued)

THERMAL METRIC		D (SOIC)	N (PDIP)	NS (SO)	UNIT
		16 PINS	16 PINS	16 PINS	
Ψ_{JT}	Junction-to-top characterization parameter	38.1	27.3	12.9	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	75.3	40.2	50.1	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	N/A	N/A	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC package thermal metrics](#) application report.

5.4 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V_{CC}	$T_A = 25^\circ\text{C}$			SN54HC109		SN74HC109		UNIT	
				MIN	TYP	MAX	MIN	MAX	MIN	MAX		
V_{OH}	$V_I = V_{IH}$ or V_{IL}	$I_{OH} = -20 \mu\text{A}$	2 V	1.9	1.998		1.9		1.9	V		
			4.5 V	4.4	4.499		4.4		4.4			
			6 V	5.9	5.999		5.9		5.9			
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84			
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34			
V_{OL}	$V_I = V_{IH}$ or V_{IL}	$I_{OL} = 20 \mu\text{A}$	2 V		0.002	0.1		0.1		0.1	V	
			4.5 V		0.001	0.1		0.1		0.1		
			6 V		0.001	0.1		0.1		0.1		
		$I_{OL} = 4 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33		
		$I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26		0.4		0.33		
I_I	$V_I = V_{CC}$ or 0		6 V		± 0.1	± 100		± 1000		± 1000	nA	
I_{CC}	$V_I = V_{CC}$ or 0, $I_O = 0$		6 V					4		80	40	μA
C_i			2 V to 6 V		3	10		10		10	pF	

5.5 Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted)

		V_{CC}	$T_A = 25^\circ\text{C}$		SN54HC109		SN74HC109		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency	2 V		6		4.2		5	MHz
		4.5 V		31		21		25	
		6 V		36		25		29	
t_w	Pulse duration	PRE or $\overline{\text{CLR}}$ low	2 V	100		150		125	ns
			4.5 V	20		30		25	
			6 V	17		25		21	
		CLK high or low	2 V	80		120		100	
			4.5 V	16		24		20	
			6 V	14		20		17	

over recommended operating free-air temperature range (unless otherwise noted)

	V_{CC}	$T_A = 25^\circ\text{C}$		SN54HC109		SN74HC109		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_{su}	Setup time before CLK \uparrow	Data (J, \bar{K})	2 V	100	150	125	ns	
			4.5 V	20	30	25		
			6 V	17	25	21		
		\overline{PRE} or \overline{CLR} inactive	2 V	25	40	30		
			4.5 V	5	8	6		
			6 V	4	7	5		
t_h	Hold time	Data after CLK \uparrow	2 V	0	0	0	ns	
			4.5 V	0	0	0		
			6 V	0	0	0		

5.6 Switching Characteristics

over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see [Figure 6-1](#))

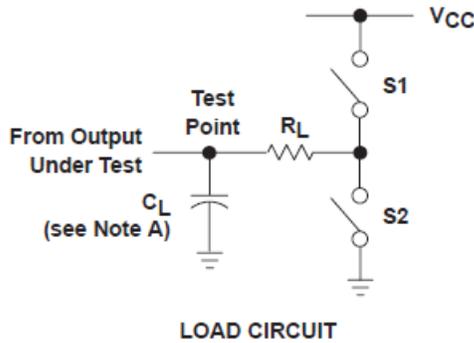
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			SN54HC109		SN74HC109		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			2 V	6	10		4.2	5	ns		
			4.5 V	31	50		21	25			
			6 V	36	60		25	29			
t_{pd}	\overline{PRE} or \overline{CLR}	Q or \bar{Q}	2 V		60	230		345	290	ns	
			4.5 V		15	46		69	58		
			6 V		12	39		59	49		
	CLK	Q or \bar{Q}	2 V		50	175		250	220		
			4.5 V		15	35		50	44		
			6 V		12	30		42	37		
t_t		Q or \bar{Q}	2 V		28	75		110	95	ns	
			4.5 V		8	15		22	19		
			6 V		6	13		19	16		

5.7 Operating Characteristics

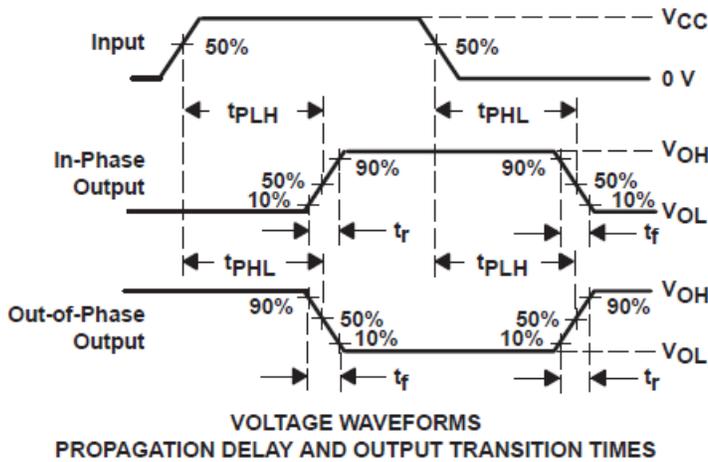
$T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per buffer/driver	35	pF

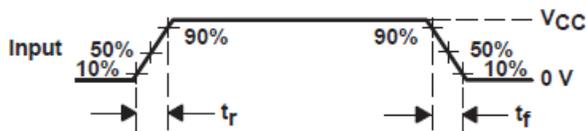
6 Parameter Measurement Information



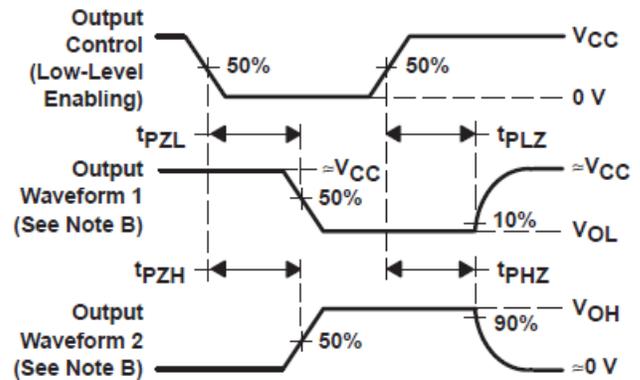
PARAMETER		R _L	C _L	S1	S2
t _{en}	t _{PZH}	1 kΩ	50 pF or 150 pF	Open	Closed
	t _{PZL}			Closed	Open
t _{dis}	t _{PHZ}	1 kΩ	50 pF	Open	Closed
	t _{PLZ}			Closed	Open
t _{pd} or t _t		--	50 pF or 150 pF	Open	Open



VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES



VOLTAGE WAVEFORM
INPUT RISE AND FALL TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

- A. C_L includes probe and test-fixture capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r = 6 ns, t_f = 6 ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. t_{PLH} and t_{PHL} are the same as t_{pd}.

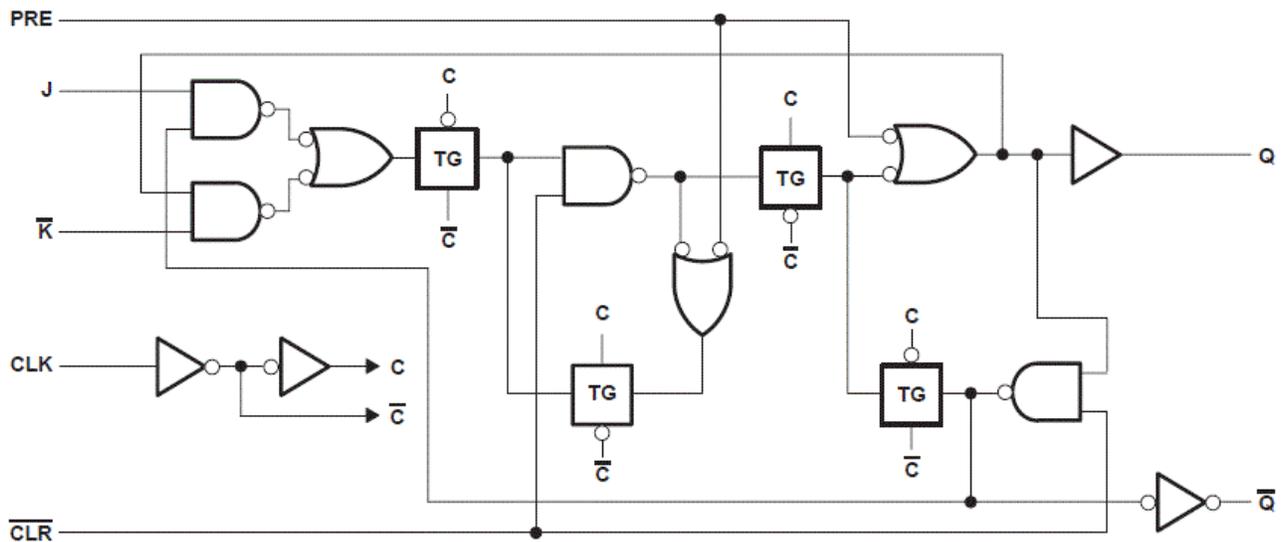
Figure 6-1. Load Circuit and Voltage Waveforms

7 Detailed Description

7.1 Overview

These devices contain two independent J-K positive-edge-triggered flip-flops. A low level at the preset (\overline{PRE}) or clear (\overline{CLR}) inputs sets or resets the outputs, regardless of the levels of the other inputs. When \overline{PRE} and \overline{CLR} are inactive (high), data at the J and \overline{K} inputs meeting the setup-time requirements are transferred to the outputs on the positive-going edge of the clock (CLK) pulse. Clock triggering occurs at a voltage level and is not related directly to the rise time of the clock pulse. Following the hold-time interval, data at the J and \overline{K} inputs can be changed without affecting the levels at the outputs. These versatile flip-flops can perform as toggle flip-flops by grounding \overline{K} and tying J high. They also can perform as D-type flip-flops if J and \overline{K} are tied together.

7.2 Functional Block Diagram



7.3 Device Functional Modes

Table 7-1. Function Table

INPUTS					OUTPUTS	
PRE	\overline{CLR}	CLK	J	\overline{K}	Q	\overline{Q}
L	H	X	X	X	H	L
H	L	X	X	X	L	H
L	L	X	X	X	H ⁽¹⁾	H ⁽¹⁾
H	H	↑	L	L	L	H
H	H	↑	H	L	Toggle	
H	H	↑	L	H	Q0	$\overline{Q0}$
H	H	↑	H	H	H	L
H	H	L	X	X	Q0	$\overline{Q0}$

(1) This configuration is nonstable; that is, it does not persist when either \overline{PRE} or \overline{CLR} returns to its inactive (high) level.

8 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Recommended Operating Conditions*. Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. A 0.1- μF capacitor is recommended for this device. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. The 0.1- μF and 1- μF capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

9 Layout

9.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices inputs must not ever be left floating. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or V_{CC} , whichever makes more sense for the logic function or is more convenient.

10 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

10.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

10.2 Support Resources

TI E2E™ [support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

10.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.

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10.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

10.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
5962-8415001VFA	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8415001VF A SNV54HC109W
5962-8415001VFA.A	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8415001VF A SNV54HC109W
84150012A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	84150012A SNJ54HC 109FK
8415001EA	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8415001EA SNJ54HC109J
8415001FA	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8415001FA SNJ54HC109W
JM38510/65304BEA	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 65304BEA
JM38510/65304BEA.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 65304BEA
M38510/65304BEA	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 65304BEA
SN54HC109J	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54HC109J
SN54HC109J.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54HC109J
SN74HC109D	Obsolete	Production	SOIC (D) 16	-	-	Call TI	Call TI	-40 to 85	HC109
SN74HC109DR	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	HC109
SN74HC109DR.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC109
SN74HC109DRG4	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC109
SN74HC109DRG4.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC109
SN74HC109N	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74HC109N
SN74HC109N.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74HC109N
SN74HC109NE4	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74HC109N
SN74HC109NSR	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC109
SN74HC109NSR.A	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC109

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SNJ54HC109FK	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	84150012A SNJ54HC 109FK
SNJ54HC109FK.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	84150012A SNJ54HC 109FK
SNJ54HC109J	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8415001EA SNJ54HC109J
SNJ54HC109J.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8415001EA SNJ54HC109J
SNJ54HC109W	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8415001FA SNJ54HC109W
SNJ54HC109W.A	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8415001FA SNJ54HC109W

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54HC109, SN54HC109-SP, SN74HC109 :

- Catalog : [SN74HC109](#), [SN54HC109](#)
- Military : [SN54HC109](#)
- Space : [SN54HC109-SP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

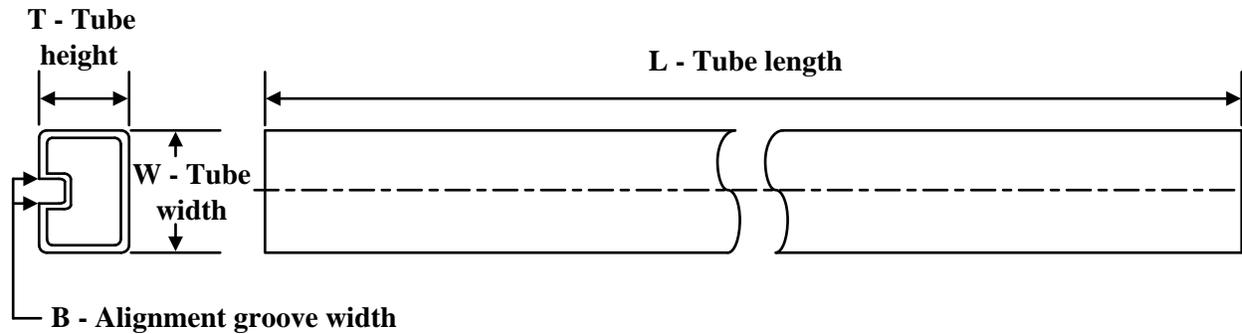

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC109DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC109DRG4	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC109NSR	SOP	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC109DR	SOIC	D	16	2500	356.0	356.0	35.0
SN74HC109DRG4	SOIC	D	16	2500	356.0	356.0	35.0
SN74HC109NSR	SOP	NS	16	2000	356.0	356.0	35.0

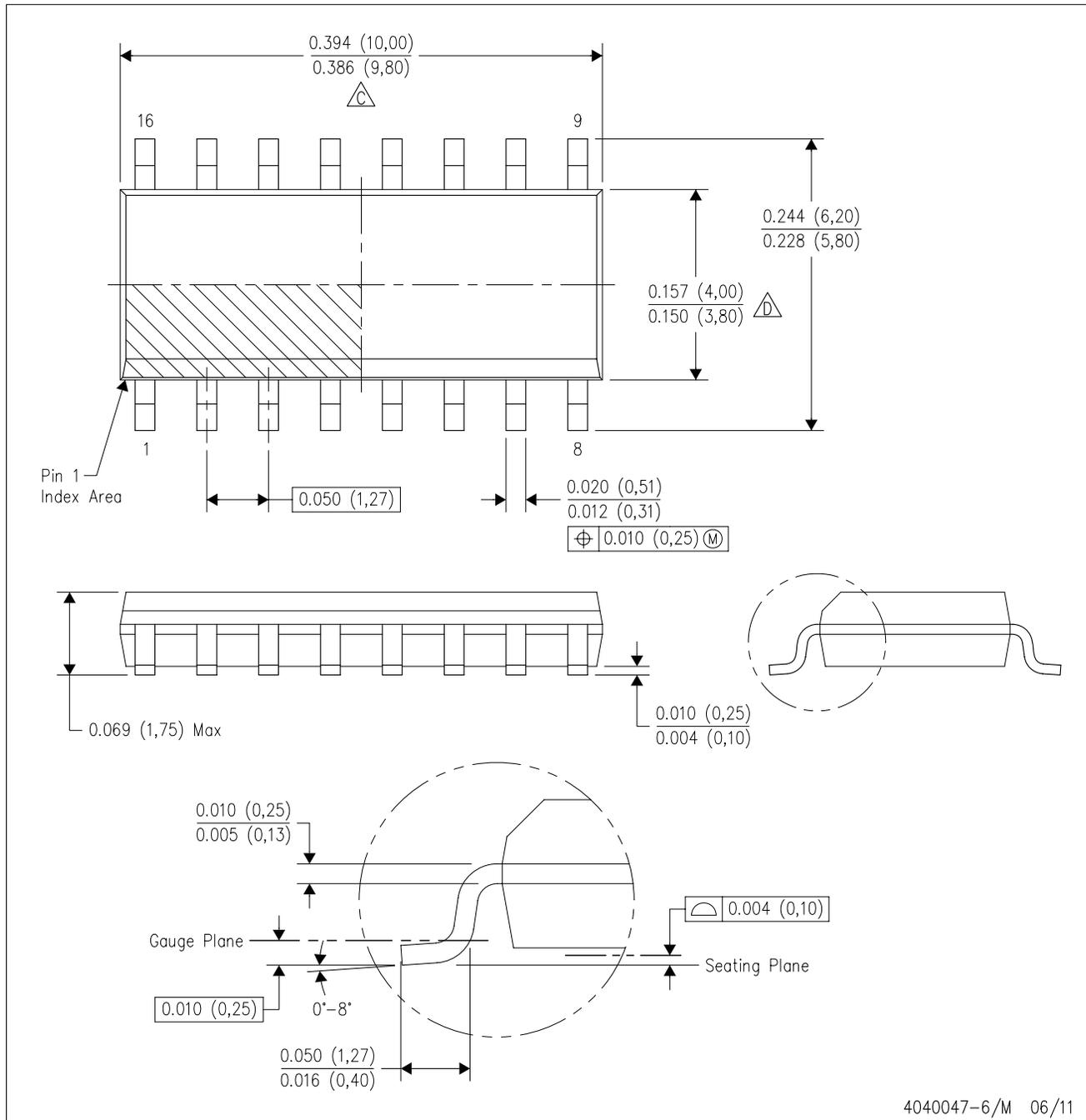
TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-8415001VFA	W	CFP	16	25	506.98	26.16	6220	NA
5962-8415001VFA.A	W	CFP	16	25	506.98	26.16	6220	NA
84150012A	FK	LCCC	20	55	506.98	12.06	2030	NA
8415001FA	W	CFP	16	25	506.98	26.16	6220	NA
SN74HC109N	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC109N	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC109N.A	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC109N.A	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC109NE4	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC109NE4	N	PDIP	16	25	506	13.97	11230	4.32
SNJ54HC109FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54HC109FK.A	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54HC109W	W	CFP	16	25	506.98	26.16	6220	NA
SNJ54HC109W.A	W	CFP	16	25	506.98	26.16	6220	NA

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



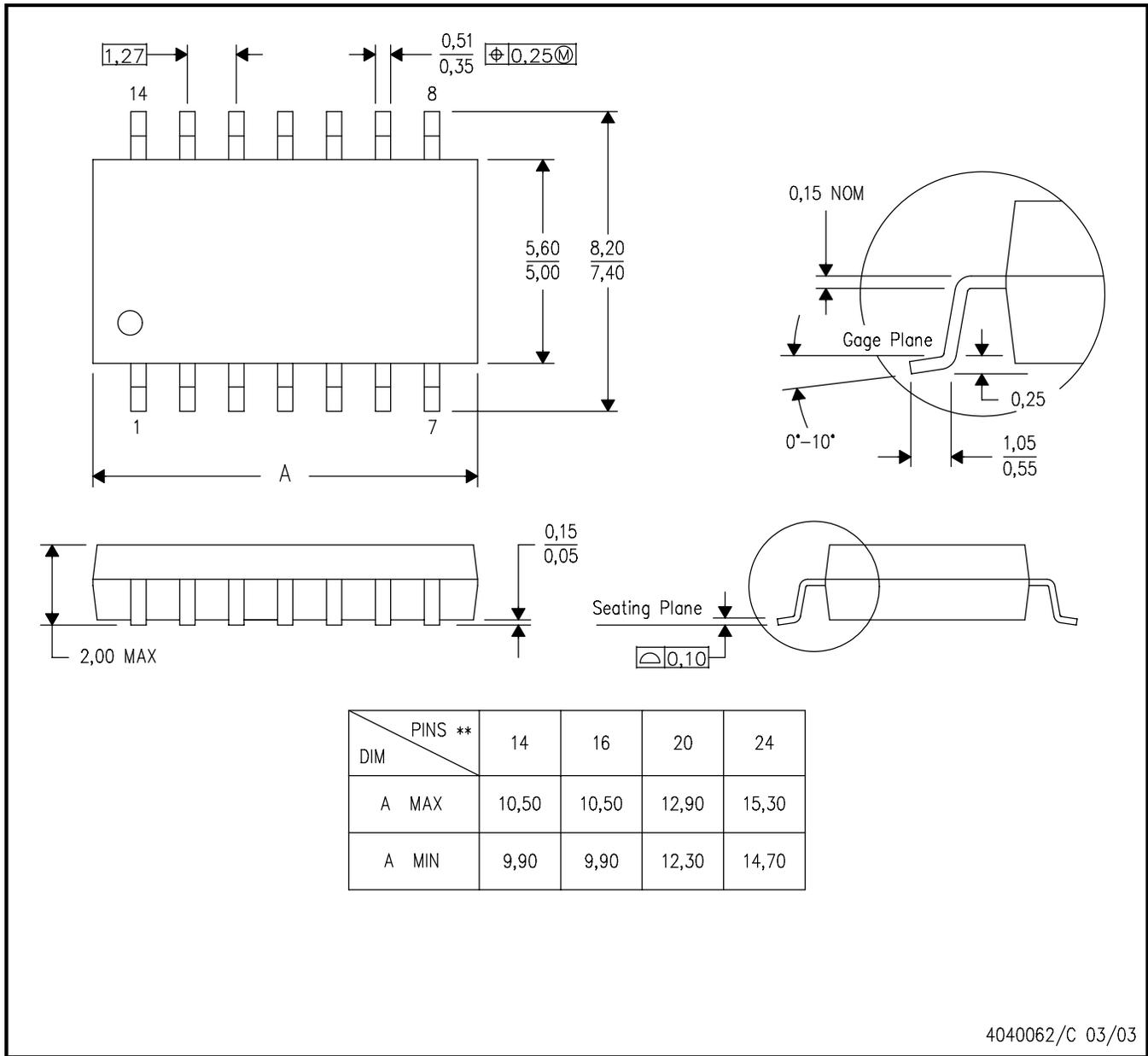
- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

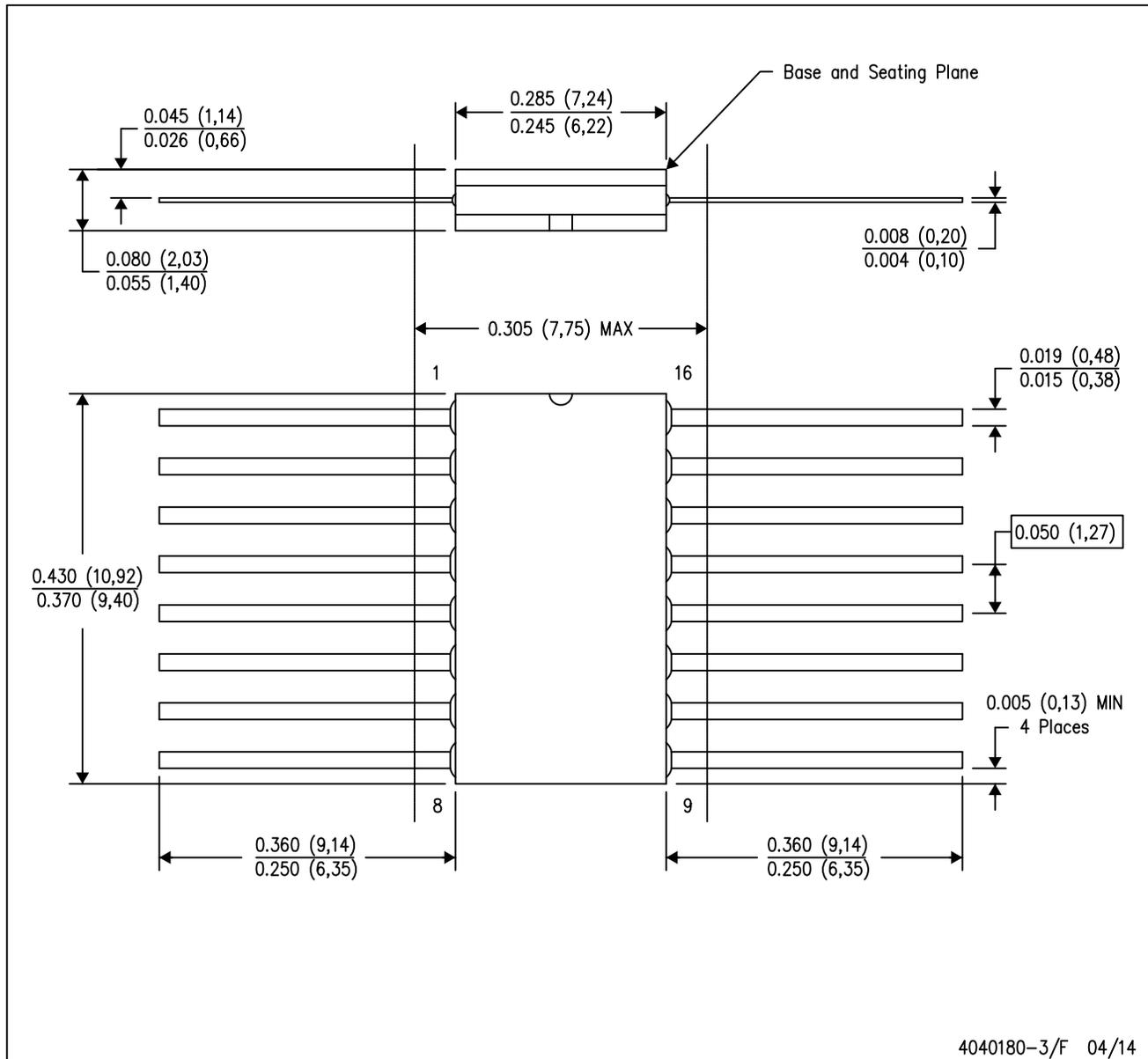
14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP2-F16

GENERIC PACKAGE VIEW

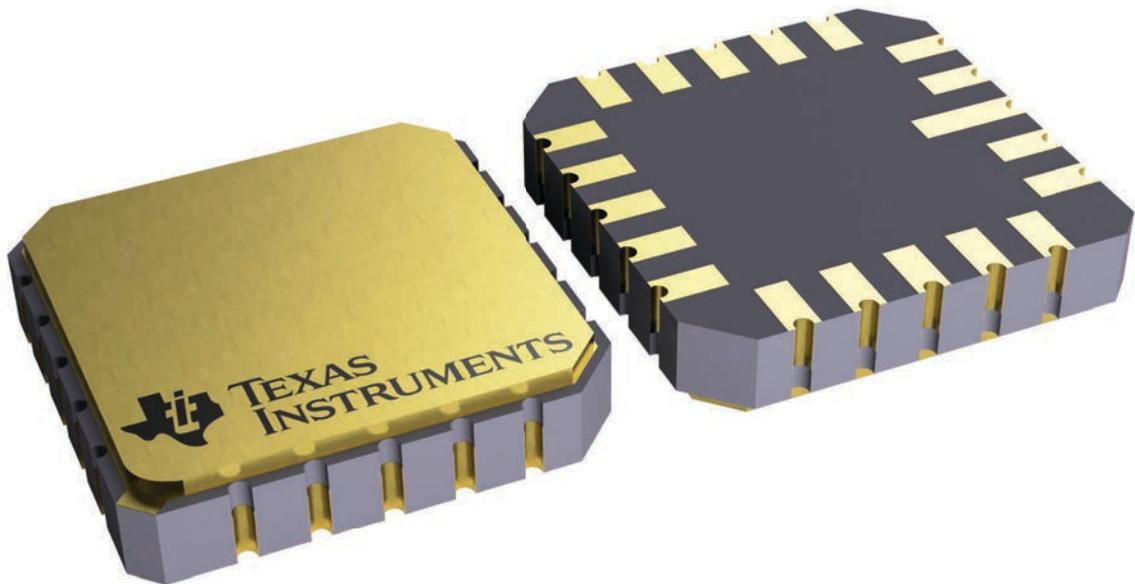
FK 20

LCCC - 2.03 mm max height

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

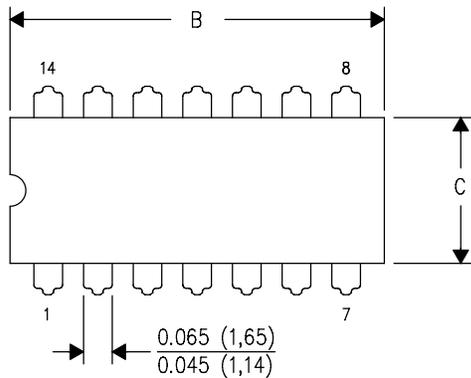


4229370VA\

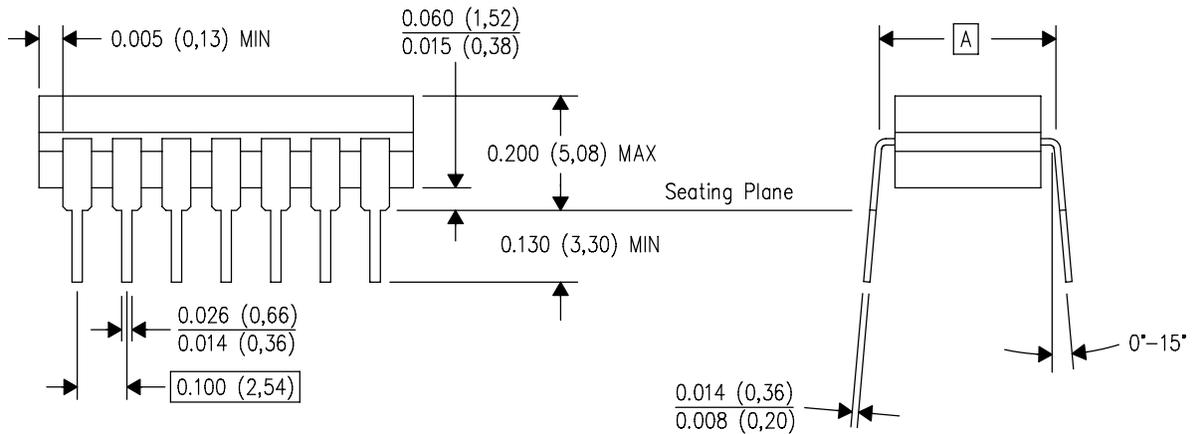
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



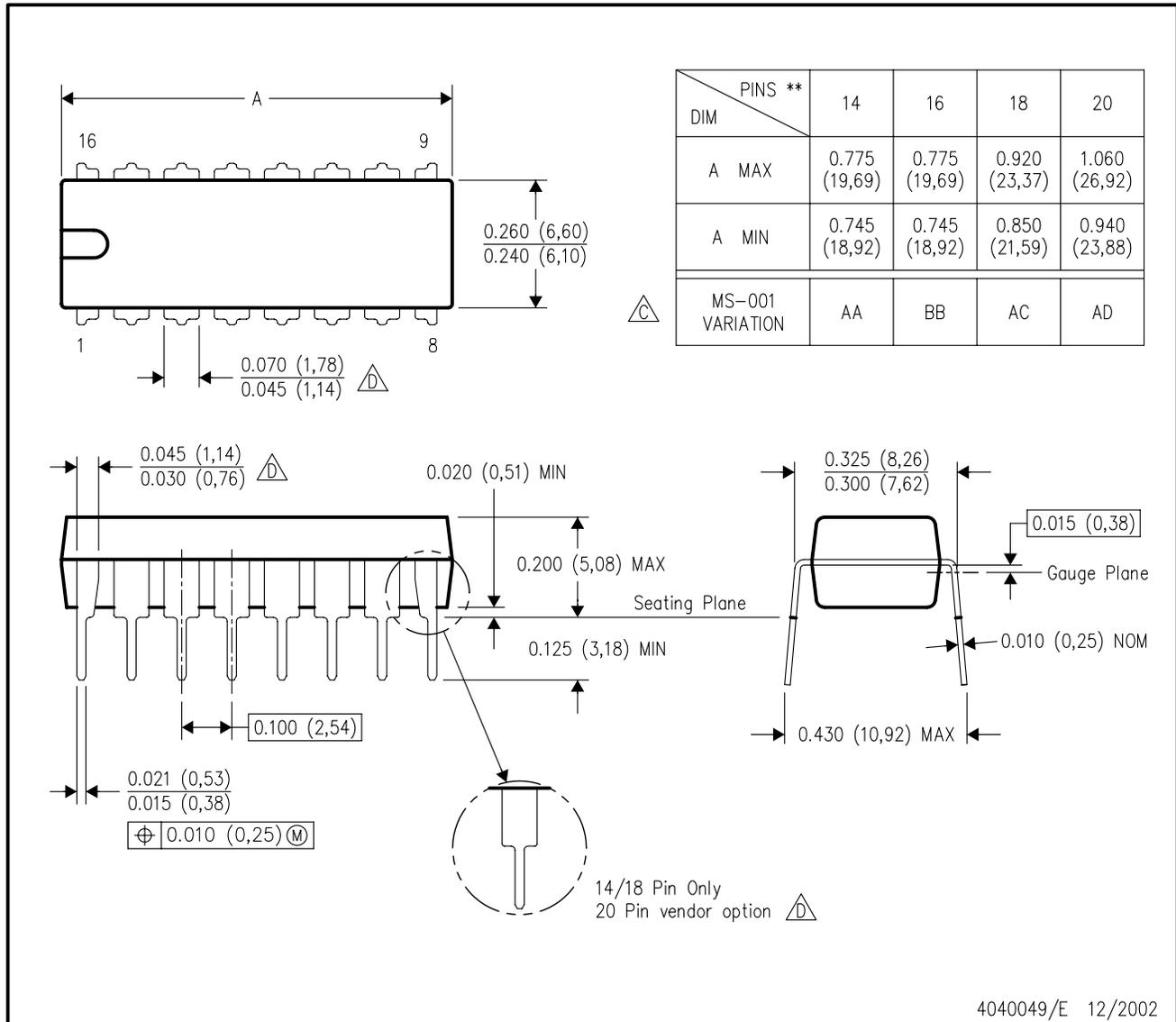
4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

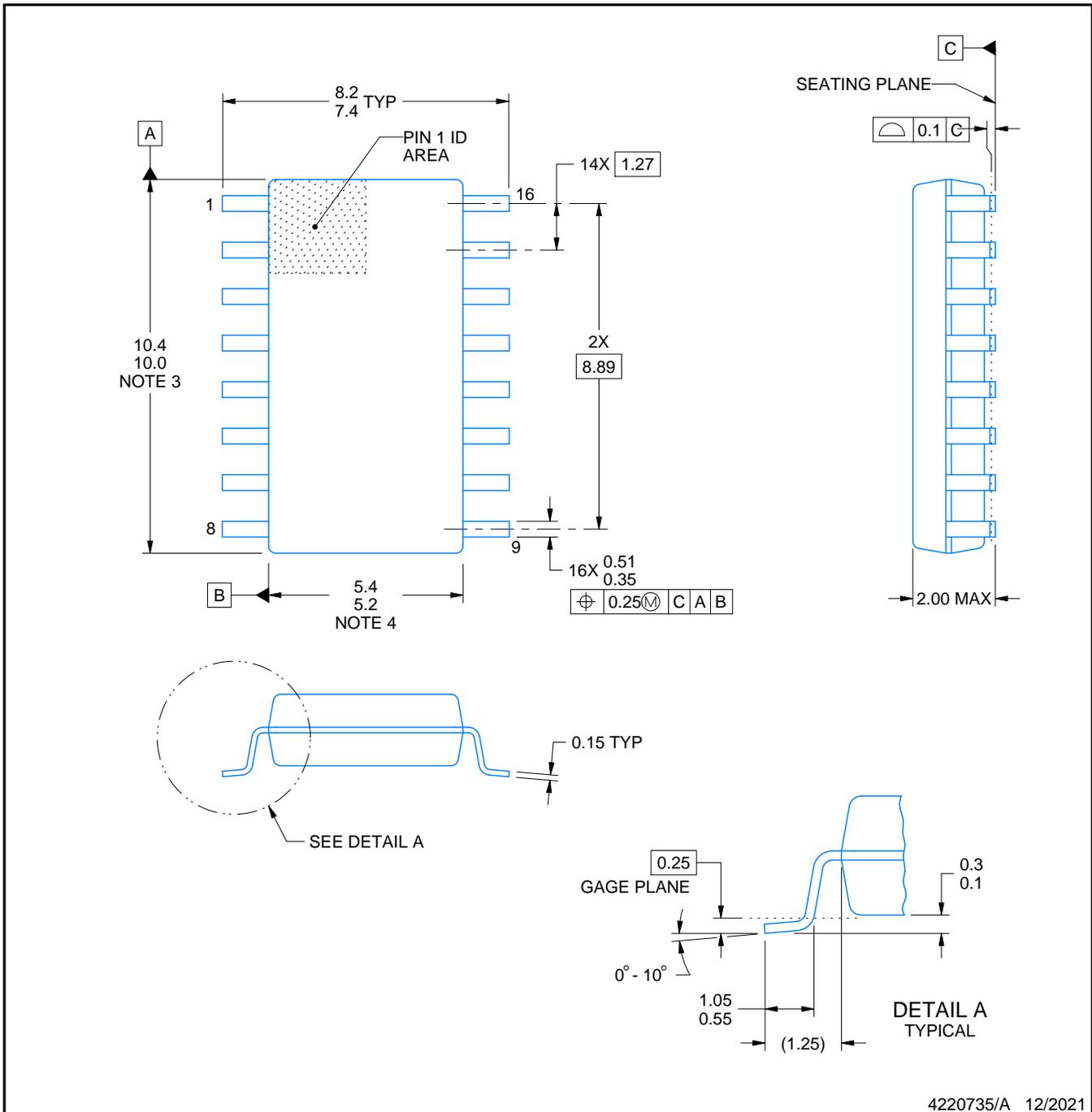


PACKAGE OUTLINE

NS0016A

SOP - 2.00 mm max height

SOP



4220735/A 12/2021

NOTES:

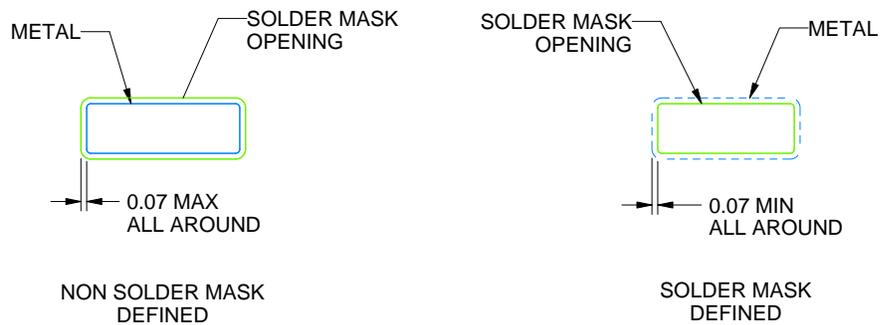
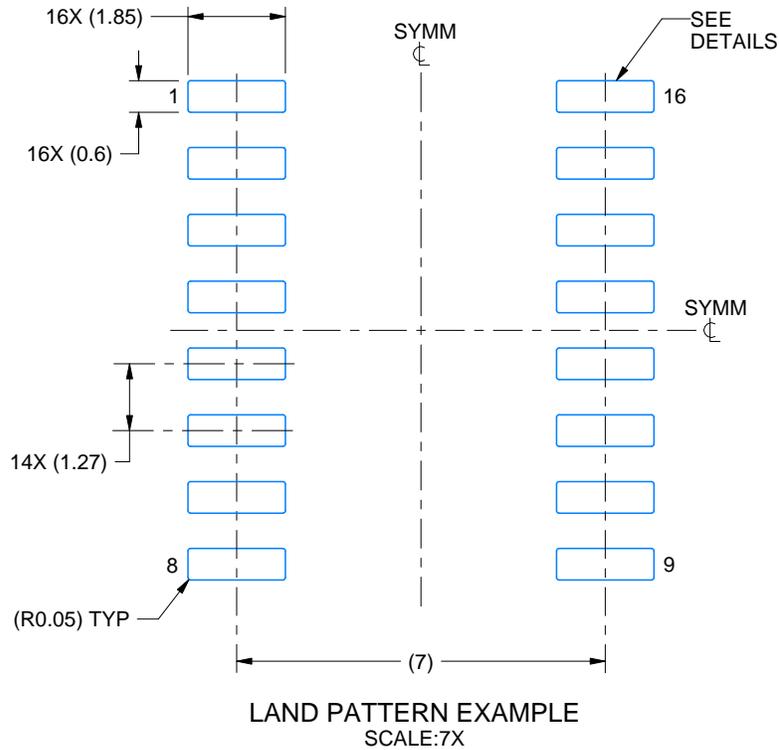
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.

EXAMPLE BOARD LAYOUT

NS0016A

SOP - 2.00 mm max height

SOP



4220735/A 12/2021

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

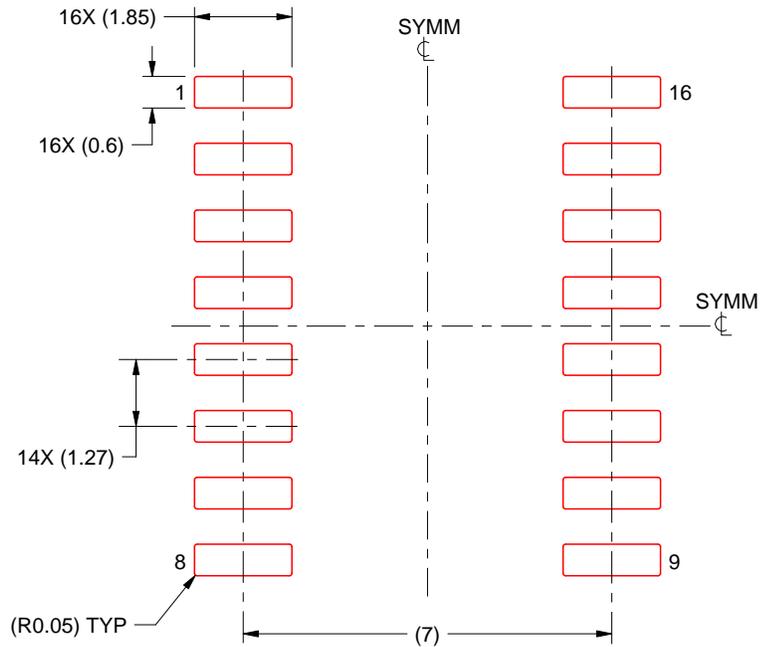
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

NS0016A

SOP - 2.00 mm max height

SOP



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

4220735/A 12/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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